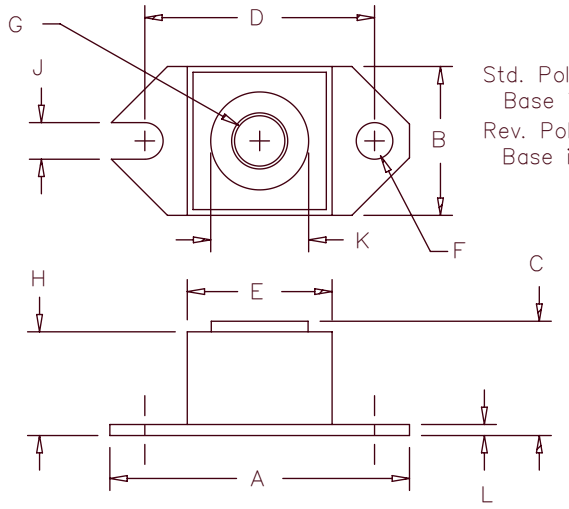
240 Amp Schottky Rectifier
HS24035 – HS24045



Std. Polarity
Base is cathode
Rev. Polarity
Base is anode

Dim.	Inches		Millimeter		
	Minimum	Maximum	Minimum	Maximum	Notes
A	1.52	1.56	38.61	39.62	
B	.725	.775	18.42	19.69	
C	.605	.625	15.37	15.88	
D	1.182	1.192	30.02	30.28	
E	.745	.755	18.92	19.18	Sq.
F	.152	.160	3.86	4.06	Dia.
G		1/4–20 UNC–2B			
H	.525	.580	13.34	14.73	
J	.156	.160	3.96	4.06	
K	.495	.505	12.57	12.83	Dia.
L	.120	.130	3.05	3.30	

Microsemi Catalog Number	Industry Part Number	Working Peak Reverse Voltage	Repetitive Peak Reverse Voltage
HS24035*	240NQ035,244NQ035 MBRP20035L,MBRP30035L MBR24035	35V	35V
HS24040*	240NQ040,244NQ040 MBR24040	40V	40V
HS24045*	240NQ045,244NQ045 MBR24045	45V	45V

*Add suffix R for Reverse Polarity

- Schottky Barrier Rectifier
- Guard ring protection
- Low forward voltage
- V_{RRM} – 35 to 45 volts
- 150°C junction temperature
- Reverse energy tested
- ROHS Compliant

Electrical Characteristics

Average forward current	$I_{F(AV)}$ 240 Amps	T_C = 92°C, square wave, $R_{\theta JC}$ = 0.24°C/W
Maximum surge current	I_{FSM} 3500 Amp	8.3 ms, half sine T_J = 150°C
Max repetitive peak reverse current	$I_{R(OV)}$ 2 Amps	f = 1 KHz, 25°C, 1µsec square wave
Max peak forward voltage	V_{FM} 0.49 Volts	I_{FM} = 240A; T_J = 125°C*
Max peak forward voltage	V_{FM} 0.55 Volts	I_{FM} = 240A; T_J = 25°C *
Max peak reverse current	I_{RM} 3.0 A	V_{RRM}, T_J = 125°C*
Max peak reverse current	I_{RM} 12 mA	V_{RRM}, T_J = 25°C
Typical junction capacitance	C_J 10500 pF	V_R = 5.0V, T_J = 25°C

*Pulse test: Pulse width 300µsec, Duty cycle 2%

Thermal and Mechanical Characteristics

Storage temp range	T_{STG}	−55°C to 175°C
Operating junction temp range	T_J	−55°C to 150°C
Maximum thermal resistance	$R_{\theta JC}$	0.24°C/W Junction to case
Typical thermal resistance (greased)	$R_{\theta CS}$	0.12°C/W Case to sink
Terminal torque		35–40 inch pounds
Mounting torque		20–25 inch pounds
Weight		1.1 ounces (28 grams)

HS24035 – HS24045

Figure 1
Typical Forward Characteristics

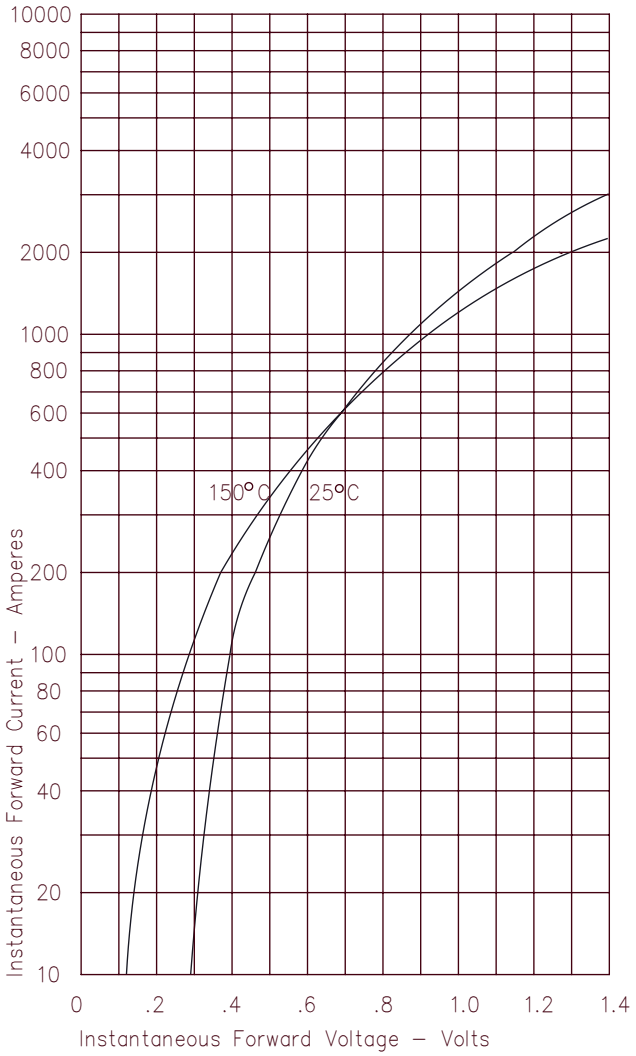


Figure 2
Typical Reverse Characteristics

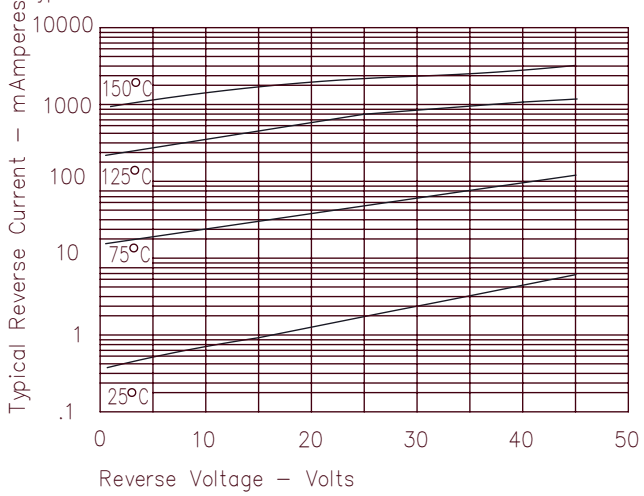


Figure 3
Typical Junction Capacitance

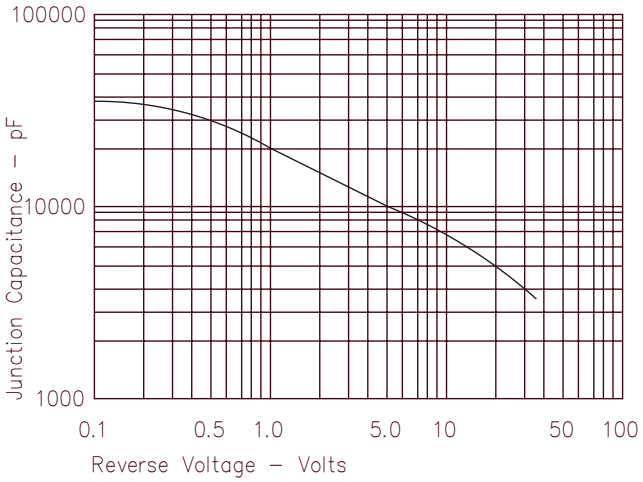


Figure 4
Forward Current Derating

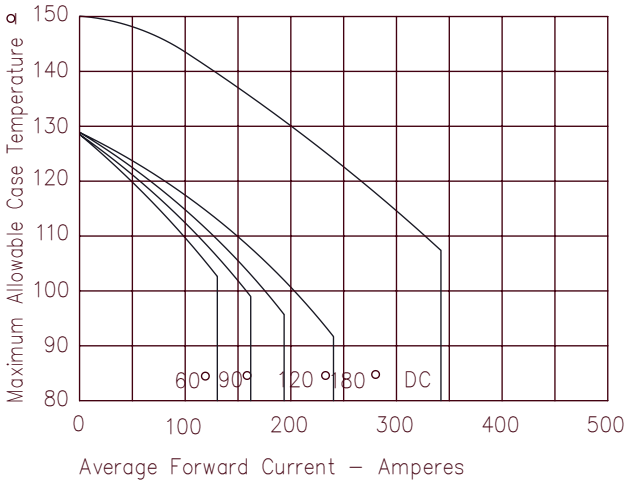
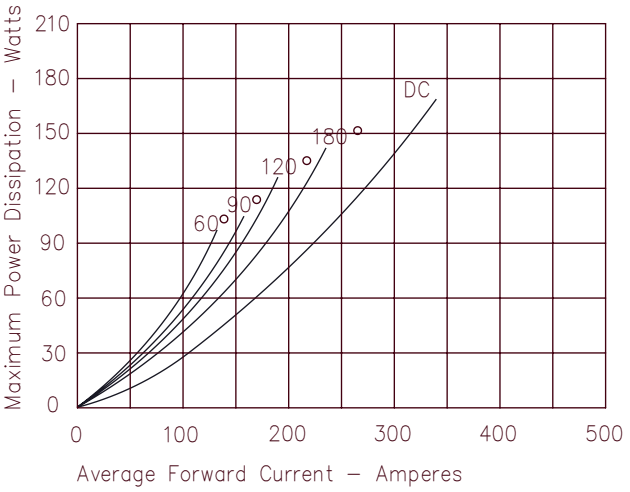


Figure 5
Maximum Forward Power Dissipation



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